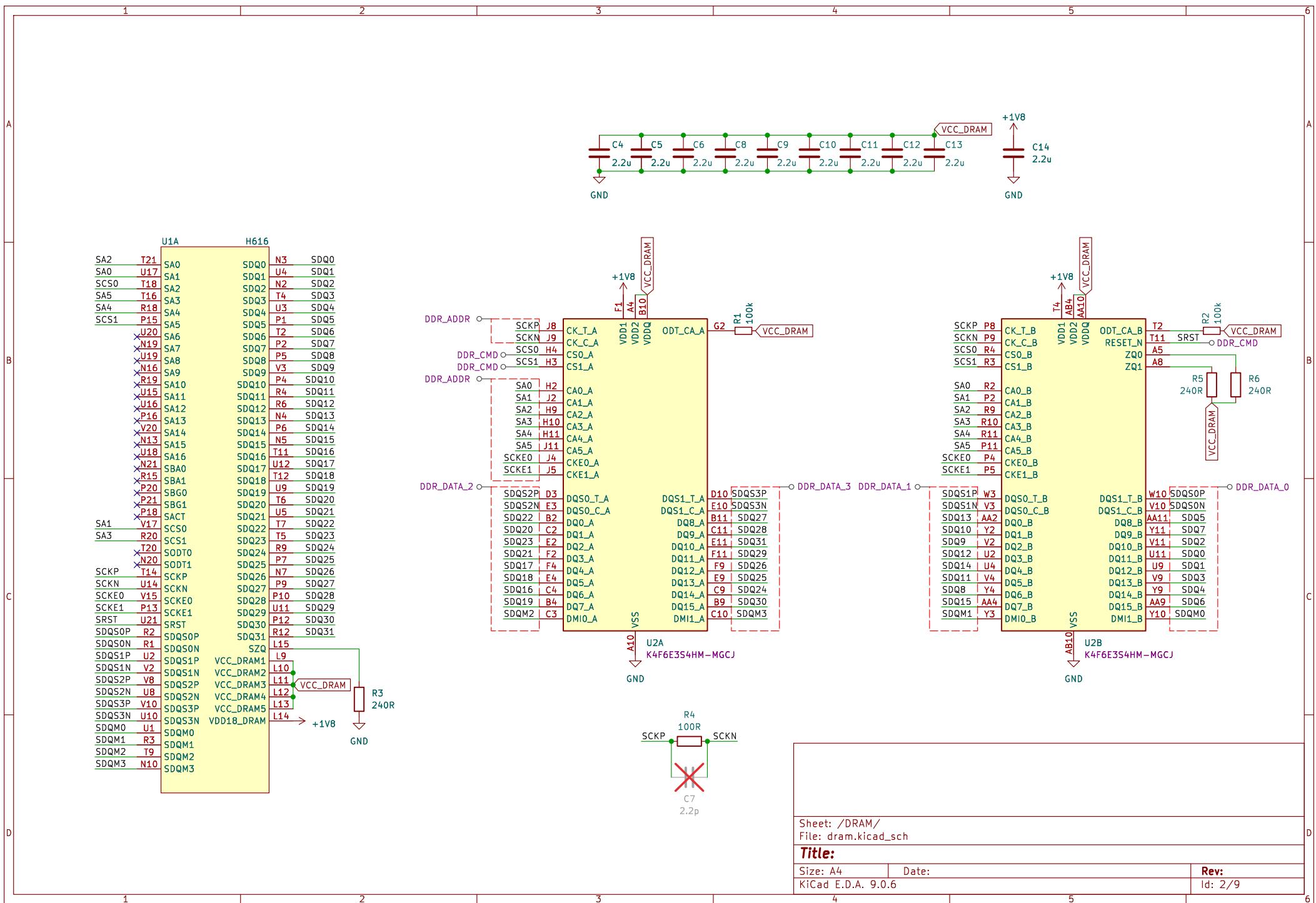
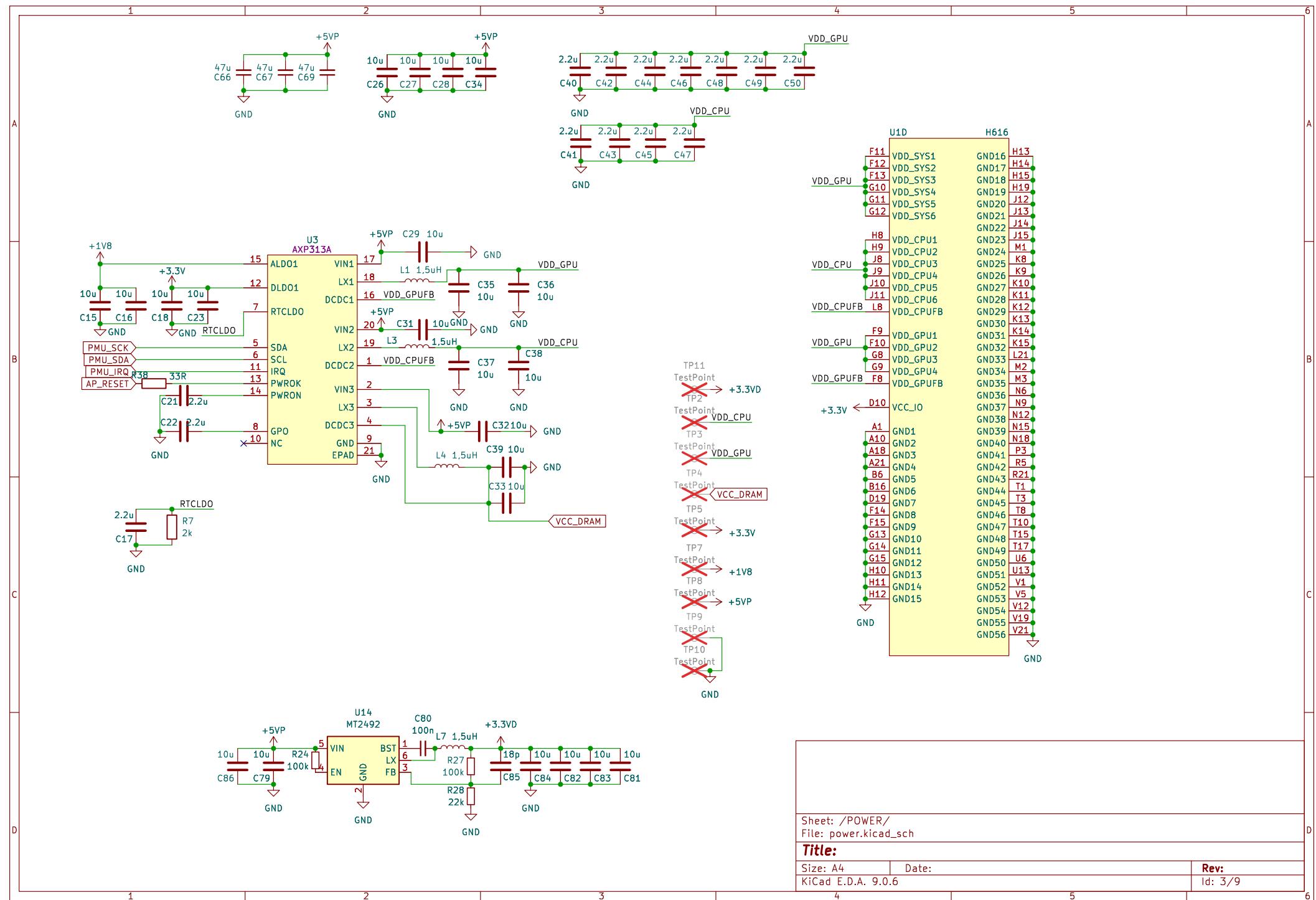
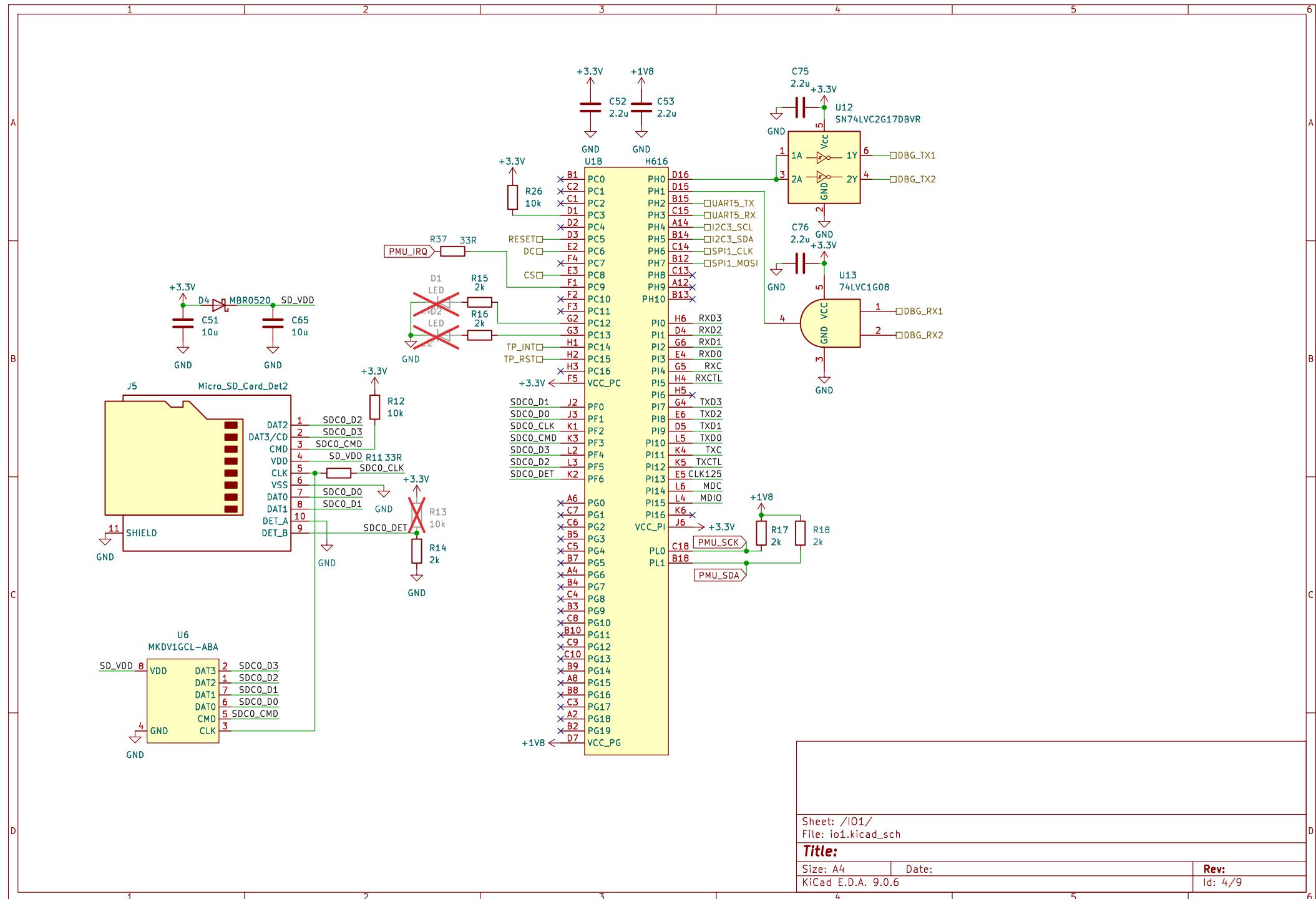


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KiCad E.D.A. 9.0.6 | Rev: Id: 1/9







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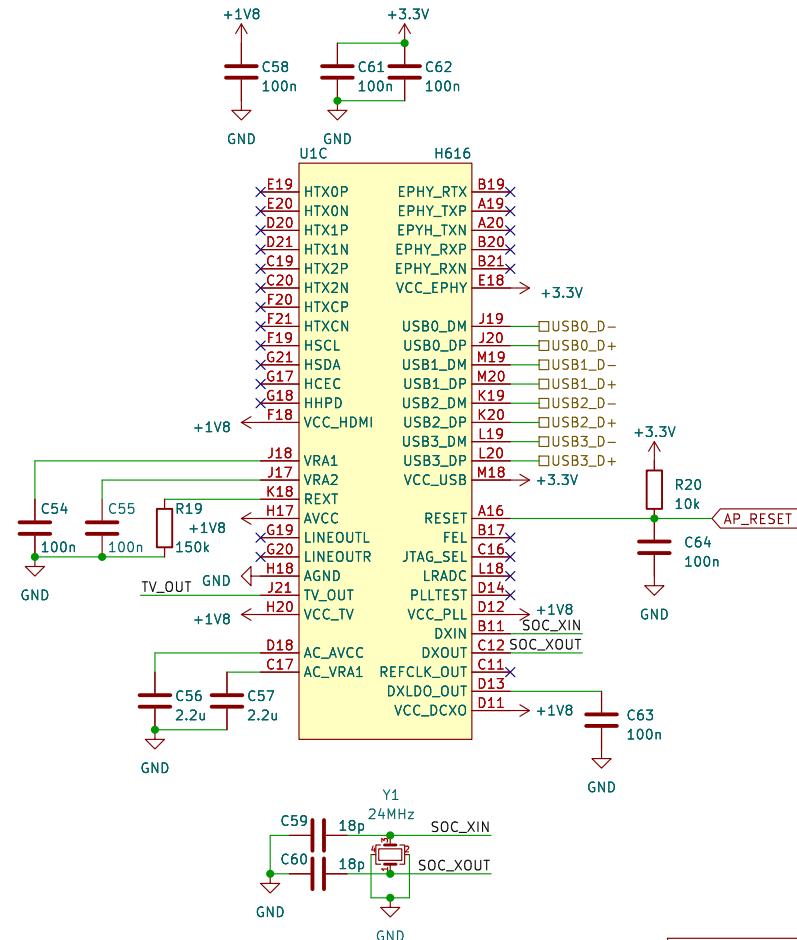
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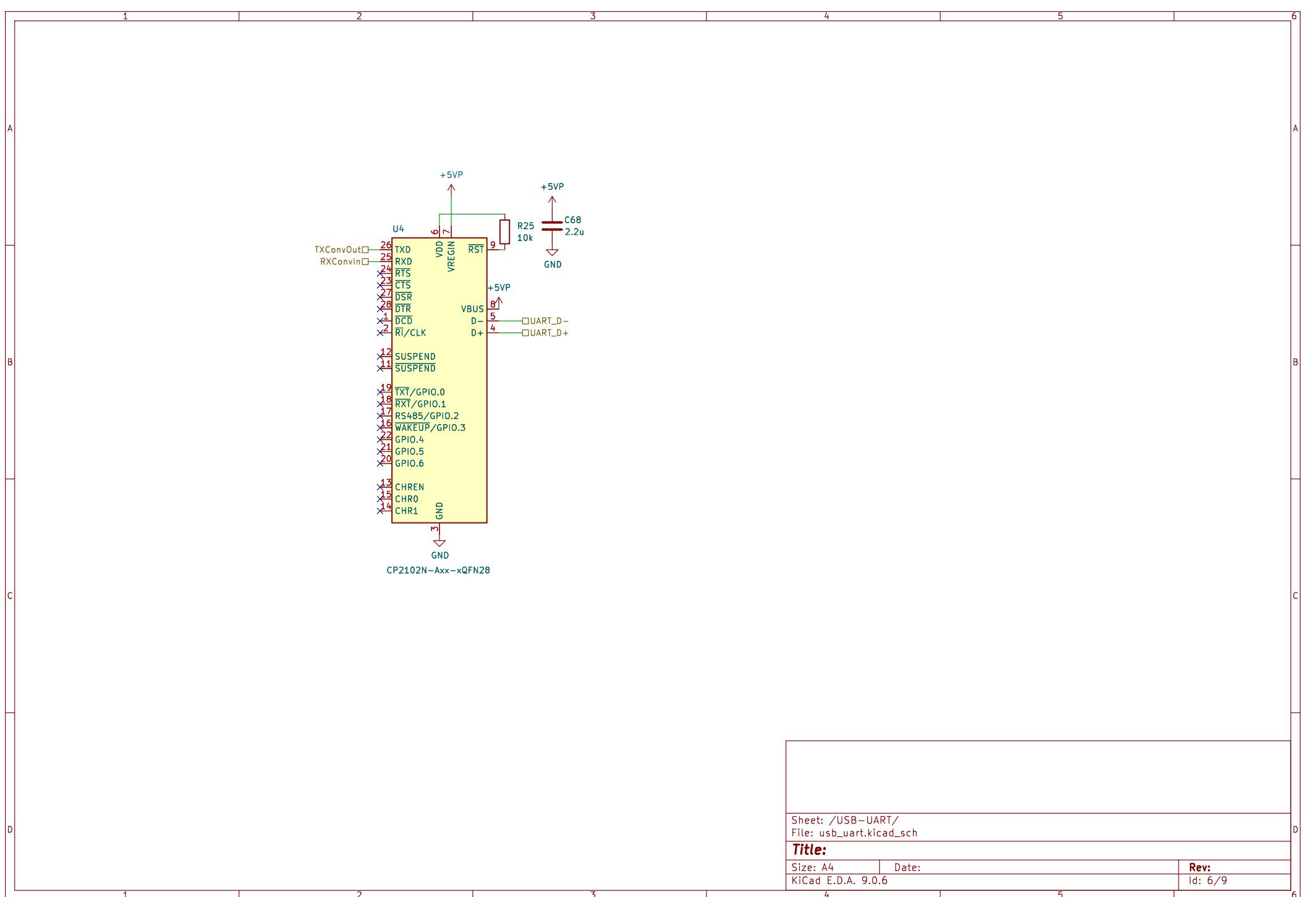


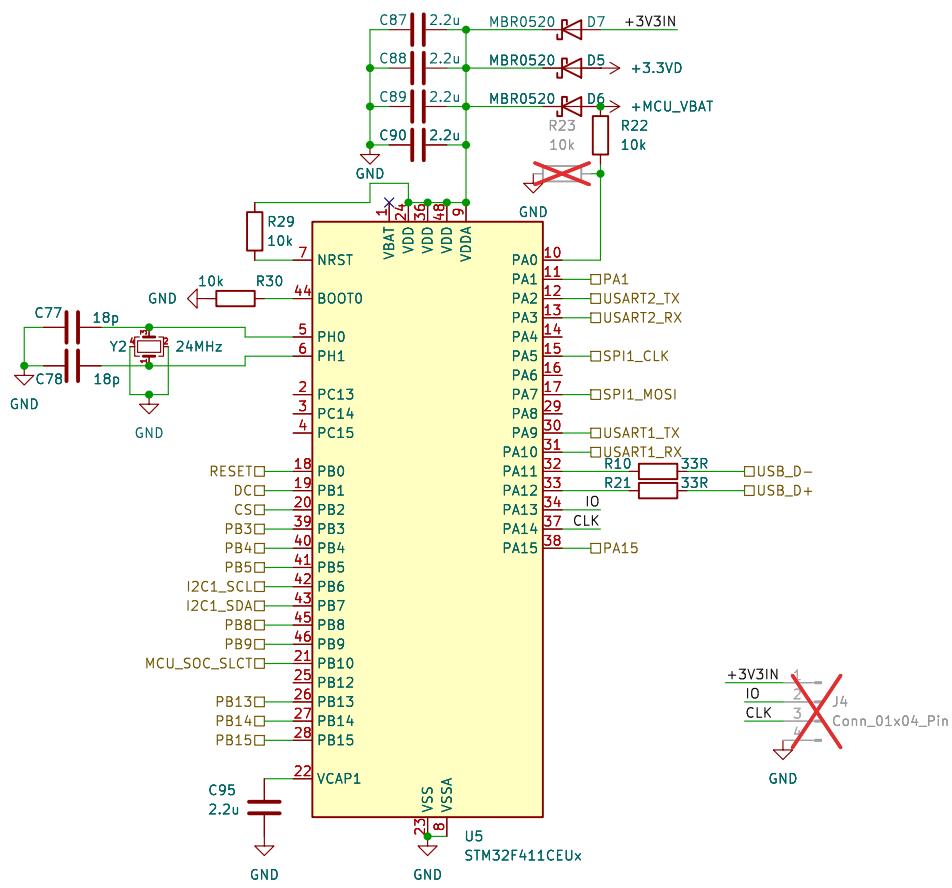
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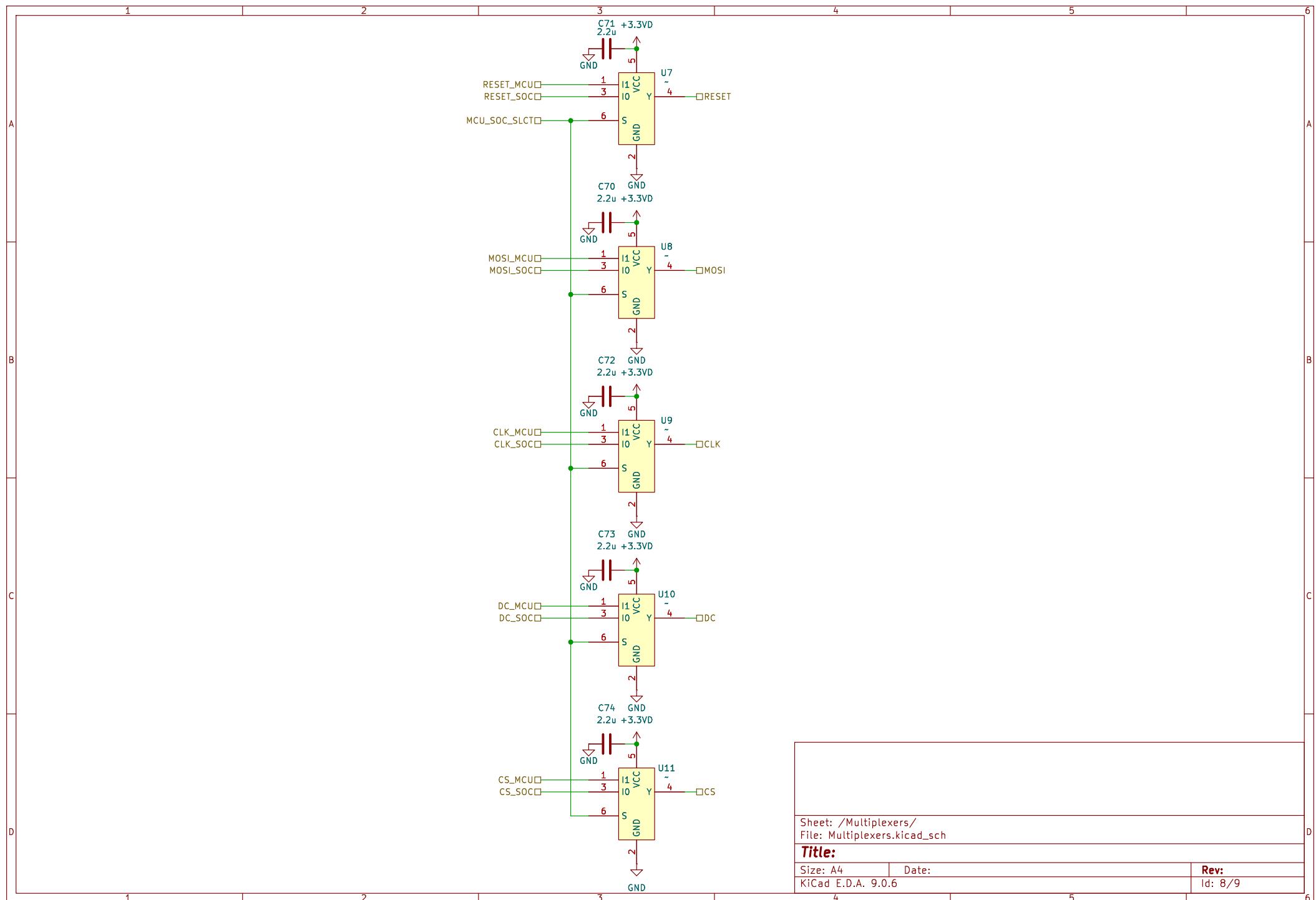


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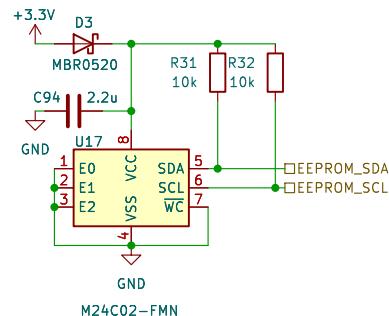
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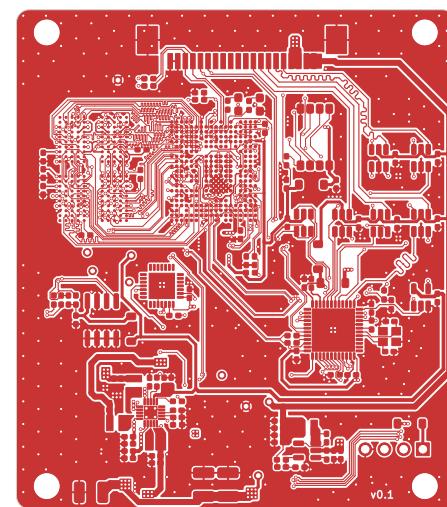
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Sheet: File: H616_devboard.kicad_pcb		D
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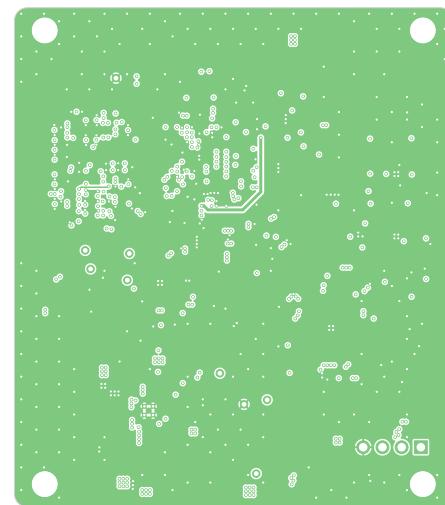
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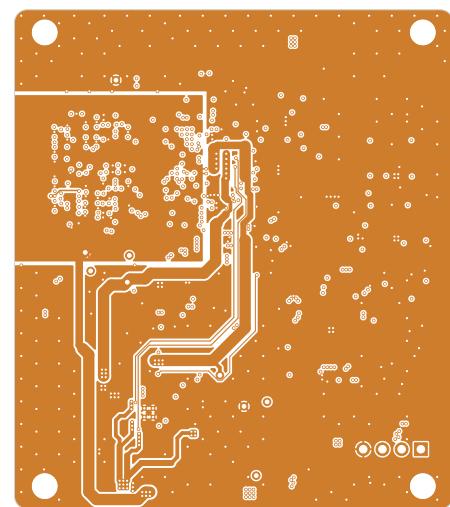
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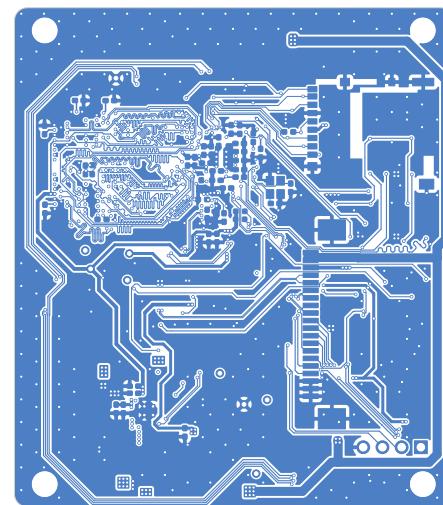
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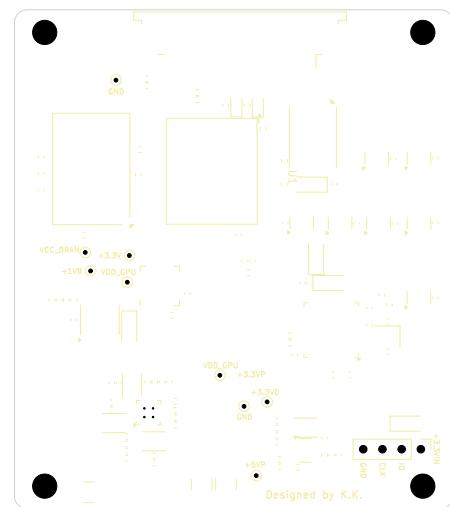
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Id: 5/9

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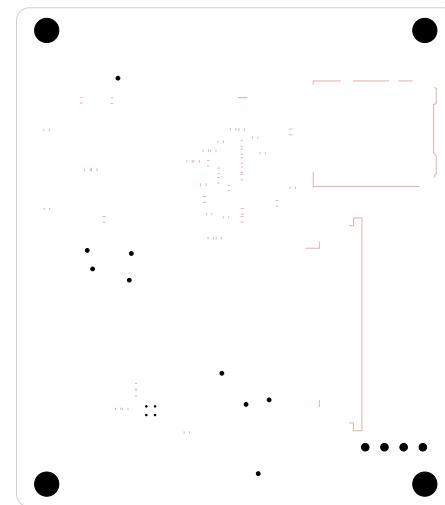
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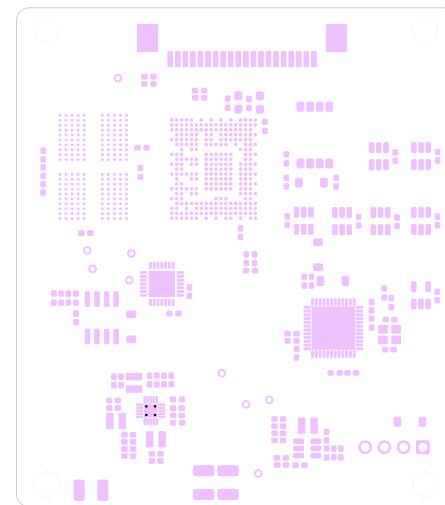
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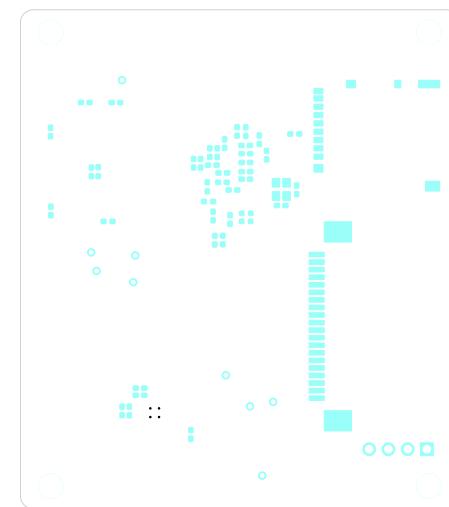
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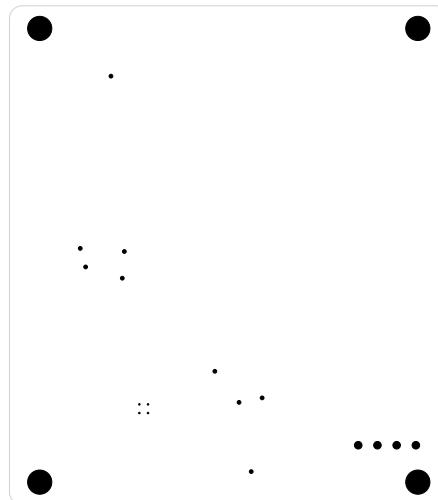
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Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.018 mm		1	0
Dielectric	prepreg	FR4	0.08 mm	Not specified	4.5	0.02
In1.Cu	copper		0.018 mm		1	0
Dielectric	core	FR4	1.3 mm	Not specified	4.5	0.02
In2.Cu	copper		0.018 mm		1	0
Dielectric	prepreg	FR4	0.08 mm	Not specified	4.5	0.02
B.Cu	copper		0.018 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

Sheet: File: H616_devboard.kicad_pcb	
Title:	
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